

a/ 1. (Amended) A case for dissipating heat from an electronic device, comprising:
an electronic circuit board;
a heat generating electronic component disposed on said circuit board; and
a housing positioned about said electronic circuit board and said heat generating
electronic component; said housing being made of a net-shaped moldable thermally
conductive composite material of a polymer base matrix with thermally conductive filler
therein; said housing being in thermal communication with said electronic component
with heat being dissipating from said heat generating electronic component and through
said housing.

a2/ 5. (Amended) A case for dissipating heat from an electronic device, comprising:
4 an electronic circuit board;
a heat generating electronic component disposed on said circuit board;
a housing positioned about said electronic circuit board and said heat generating
electronic component; said housing being of a net-shaped moldable thermally
conductive composite material of a polymer base matrix with thermally conductive filler
therein;
a protrusion emanating from said housing corresponding and aligned with said
heat generating electronic component; said protrusion emanating from said housing;
and
said protrusion being in thermal communication with said electronic component
with heat being dissipating from said heat generating electronic component and through
said housing via said protrusion.

938. (Amended) A case for dissipating heat from an electronic device, comprising:

an electronic circuit board;

a heat generating electronic component, having a top surface, disposed on said circuit board;

an electromagnetic interference shield positioned on said electronic circuit board with said heat generating electronic component residing therebetween; said electromagnetic interference shield including a top surface with an aperture therethrough;

a heat transfer conduit molded into and through said aperture; said heat transfer conduit being made of a thermally conductive material and having a top surface and a bottom surface;

a housing, being made of a net-shaped moldable thermally conductive composite material of a polymer base matrix with thermally conductive filler therein, being in thermal communication with said top surface of said heat transfer conduit; said bottom surface of said heat transfer conduit being in thermal communication with said top surface of said heat generating electronic component;

whereby heat is dissipated from said heat generating electronic component via said heat transfer conduit through said electromagnetic interference shield and out said housing while said electromagnetic interference shield protects said heat generating electronic component from electromagnetic interference.

REMARKS

Claims 1, 5 and 9 have been amended and Claims 2, 6 and 10 have been canceled. Claims 1, 3-5 and 7-9, 11 and 12 now remain pending in this application.